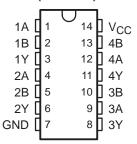
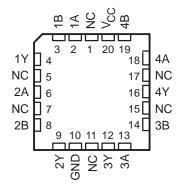
- 4.5-V to 5.5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V

SN54ACT32...J OR W PACKAGE SN74ACT32...D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



- Max t_{pd} of 10 ns at 5 V
- Inputs Are TTL-Voltage Compatible

SN54ACT32 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

The 'ACT32 devices are quadruple 2-input positive-OR gates. The devices perform the Boolean function Y = A + B or $Y = \overline{A} \bullet \overline{B}$ in positive logic.

ORDERING INFORMATION

TA	PACKAGI	ΕŤ	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – N	Tube	SN74ACT32N	SN74ACT32N	
–40°C to 85°C	colo p	Tube	SN74ACT32D	ACTOO	
	SOIC - D	Tape and reel	SN74ACT32DR	ACT32	
	SOP - NS	Tape and reel	SN74ACT32NSR	ACT32	
	SSOP – DB	Tape and reel	SN74ACT32DBR	AD32	
	TOCOD DW	Tube	SN74ACT32PW	4000	
	TSSOP – PW	Tape and reel	SN74ACT32PWR	AD32	
	CDIP – J	Tube	SNJ54ACT32J	SNJ54ACT32J	
–55°C to 125°C	CFP – W	Tube	SNJ54ACT32W	SNJ54ACT32W	
	LCCC - FK	Tube	SNJ54ACT32FK	SNJ54ACT32FK	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each gate)

	(000:	gato
INP	UTS	OUTPUT
Α	В	Υ
Н	Х	Н
Х	Н	Н
L	L	L



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}		
Input voltage range, V _I (see Note 1)		–0.5 V to V _{CC} + 0.5 V
Output voltage range, VO (see Note 1)		–0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$).		±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CO}	c)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})		±50 mA
Continuous current through V _{CC} or GND		±200 mA
Package thermal impedance, θ _{JA} (see Note 2)	: D package	86°C/W
	DB package	96°C/W
	N package	80°C/W
	NS package	76°C/W
	PW package	113°C/W
Storage temperature range, T _{sta}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

		SN54ACT		CT32 SN74A		UNIT
		MIN	MAX	MIN	MAX	UNII
VCC	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	in	2		V
VIL	Low-level input voltage		0.8		8.0	V
VI	Input voltage	0	Vcc	0	VCC	V
VO	Output voltage	0	VCC	0	VCC	V
ЮН	High-level output current	ng	-24		-24	mA
loL	Low-level output current	08	24		24	mA
Δt/Δν	Input transition rise or fall rate	Q	8		8	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEGT CONDITIONS	.,	T _A = 25°C			SN54A	CT32	SN74ACT32		UNIT	
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII	
	Jan. 50 nA	4.5 V	4.4			4.4		4.4			
	$IOH = -50 \mu A$	5.5 V	5.4			5.4		5.4			
VOH	Jan. 24 mA	4.5 V	3.86			3.7		3.76		.,	
	I _{OH} = -24 mA	5.5 V	4.86			4.7		4.76		V	
	I _{OH} = -50 mA [†]	5.5 V				3.86					
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V					EN	3.85			
	I _{OL} = 50 μA			0.001	0.1		0.1		0.1		
				0.001	0.1	.<	0.1		0.1		
V	I _{OL} = 24 mA	5.5 V			0.36	Ź	0.5		0.44	V	
VOL		5.5 V			0.36	g	0.5		0.44		
	I _{OL} = 50 mA [†]	5.5 V				y.	1.65				
	I _{OL} = 75 mA [†]								1.65		
lį	$V_I = V_{CC}$ or GND	5.5 V			±0.1		±1		±1	μΑ	
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		40		20	μΑ	
Δl _{CC} ‡	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V		0.6			1.6		1.5	mA	
C _i	V _I = V _{CC} or GND	5 V		2.6						pF	

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V $\,\pm\,$ 0.5 V (unless otherwise noted) (see Figure 1)

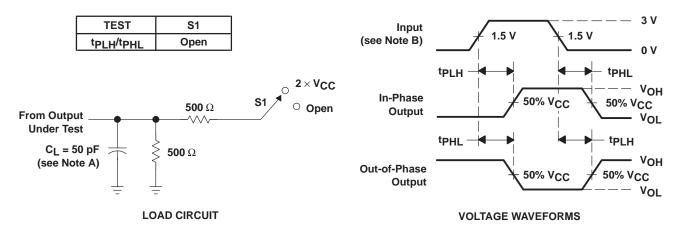
DADAMETER	FROM	то	T _A = 25°C			SN54ACT32	SN74ACT32		LINUT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN MAX	MIN	MAX	UNIT
^t PLH	A == D	V	1	6.5	9	SEOFAIL	1	10	20
t _{PHL}	A or B	1	1	6.5	9	Sk.	1	10	ns

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST C	TYP	UNIT	
C _{pd}	Power dissipation capacitance	C _L = 50 pF,	f = 1 MHz	40	pF

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5$ ns. $t_f \leq 2.5$ ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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4-Jun-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ACT32D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32DBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74ACT32DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ACT32NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ACT32NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32PWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32PWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74ACT32PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ACT32PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.



PACKAGE OPTION ADDENDUM

4-Jun-2007

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT32DBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74ACT32DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ACT32NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74ACT32PWR	TSSOP	PW	14	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1





*All dimensions are nominal

7 til dillionorio di o mornina							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ACT32DBR	SSOP	DB	14	2000	346.0	346.0	33.0
SN74ACT32DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74ACT32NSR	SO	NS	14	2000	346.0	346.0	33.0
SN74ACT32PWR	TSSOP	PW	14	2000	346.0	346.0	29.0

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.

